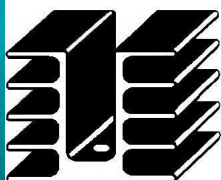


HEATPIPE ASSEMBLIES THERMAL MANAGEMENT

MAKING YOUR HEATPIPE ASSEMBLY MOST
EFFICIENT AND THERMALLY BEST



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HALA THERMAL INTERFACE SOLUTIONS

Phase Change

Films

TPC-Z-PC

TPC-T-AL-CB

TPC-S-AL

Printable

TPC-Z-PC-P

TPC-X-PC-NC

Dispensable

TPC-Z-PC-D

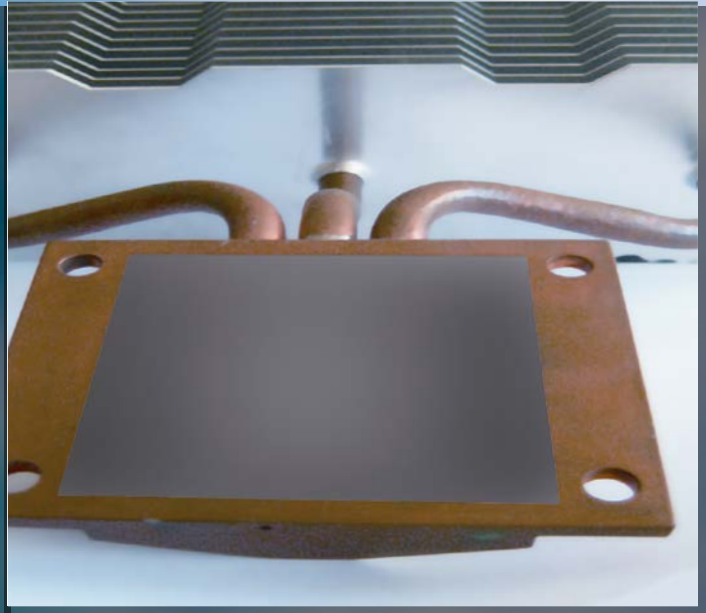
Graphite foil

TFO-S-CB

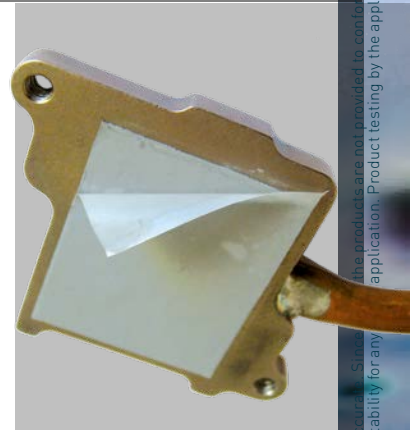
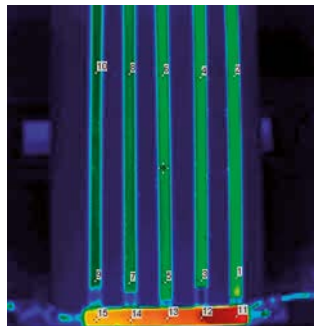
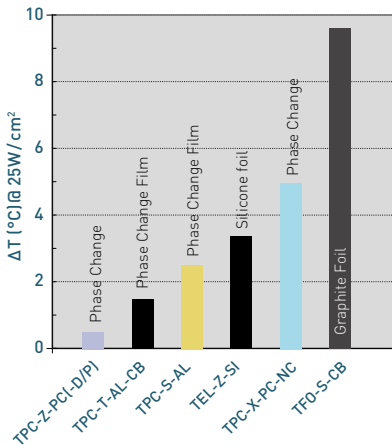
Silicone foil

TEL-Z-SI

Please contact us as your development partner.



ΔT DATA

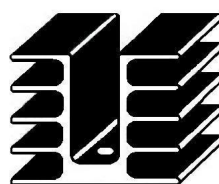


CREATING

- Maximum thermal contact
- Minimized thermal resistance
- Compensating mechanic tolerances
- Enhancing efficiency

BENEFITS

- Increasing long-term reliability
- Homogenizing temperatures
- Pre-applied dry-to-the-touch



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